

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



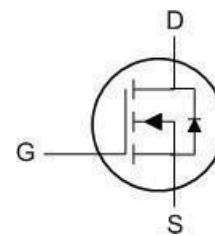
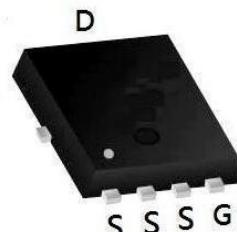
BVDSS	RDS(ON)	ID
20V	6.3 mΩ	40A

Description

The XXW40N02D is the high cell density trench N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XXW40N02D meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

PDFN3*3 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	40	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	23	A
I_{DM}	Pulsed Drain Current ²	210	A
EAS	Single Pulse Avalanche Energy ³	36	mJ
I_{AS}	Avalanche Current	21	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation ⁴	15	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
R_{eJC}	Thermal Resistance Junction-Case ¹	4.8	°C/W

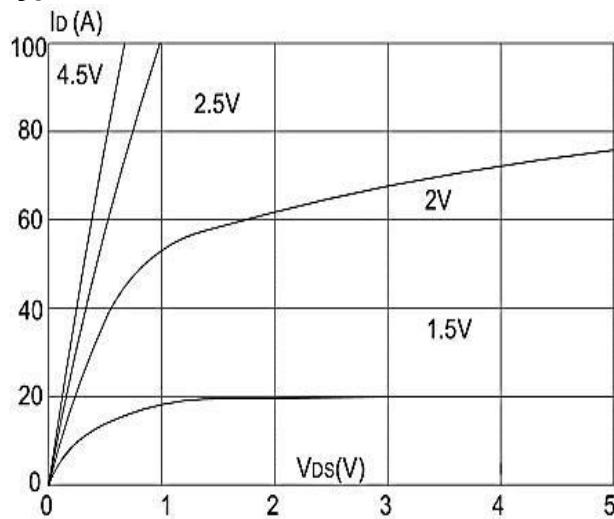
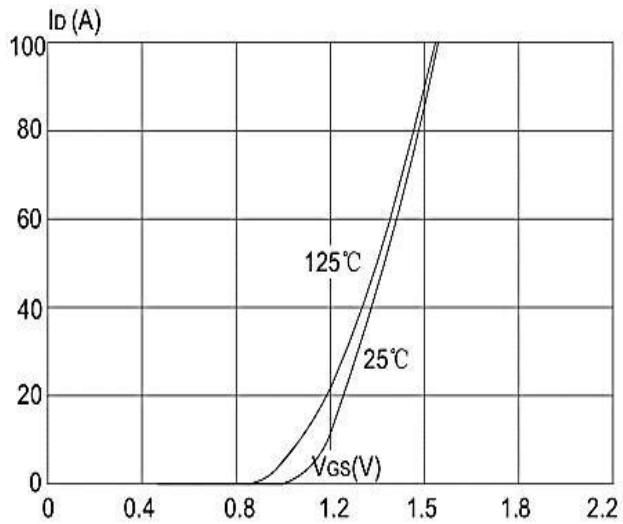
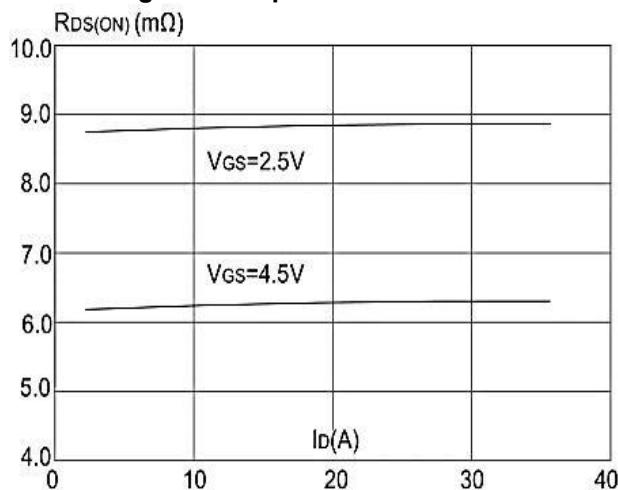
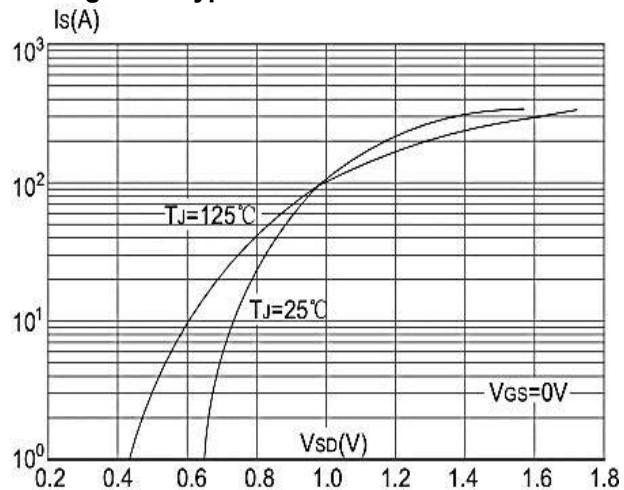
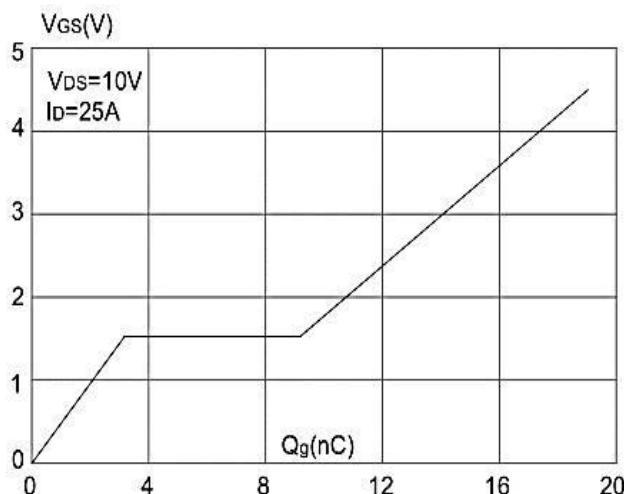
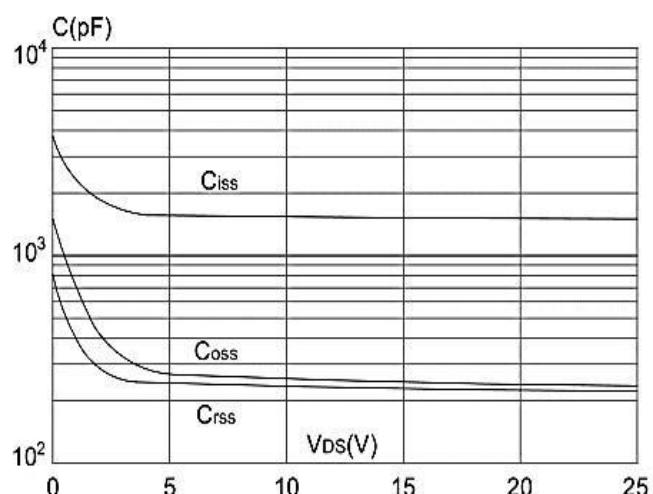
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.4	0.7	1.1	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=4.5\text{V}$, $I_D=25\text{A}$	-	6.3	8.0	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=10\text{A}$	-	8.8	13	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	1458	-	pF
C_{oss}	Output Capacitance		-	238	-	pF
C_{rss}	Reverse Transfer Capacitance		-	212	-	pF
Q_g	Total Gate Charge	$V_{DS}=10\text{V}$, $I_D=25\text{A}$, $V_{GS}=4.5\text{V}$	-	19	-	nC
Q_{gs}	Gate-Source Charge		-	3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	6.4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10\text{V}$, $I_D=10\text{A}$, $R_{\text{GEN}}=3\Omega$, $V_{GS}=4.5\text{V}$	-	10	-	ns
t_r	Turn-on Rise Time		-	21	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	39	-	ns
t_f	Turn-off Fall Time		-	19	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	200	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=30\text{A}$	-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$IF=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	25	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	20	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=10\text{V}$, $V_G=4.5\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$, $I_{AS}=12\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Characteristics

Figure 1: Output Characteristics

Figure 2: Typical Transfer Characteristics

Figure 3: On-resistance vs. Drain Current

Figure 4: Body Diode Characteristics

Figure 5: Gate Charge Characteristics

Figure 6: Capacitance Characteristics

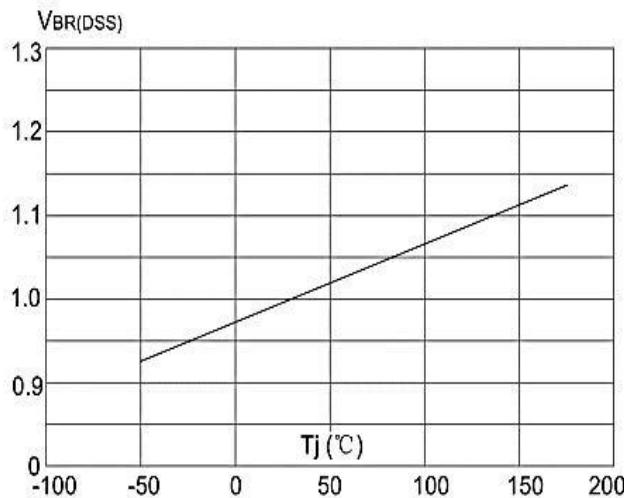
N-Ch 20V Fast Switching MOSFETs


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

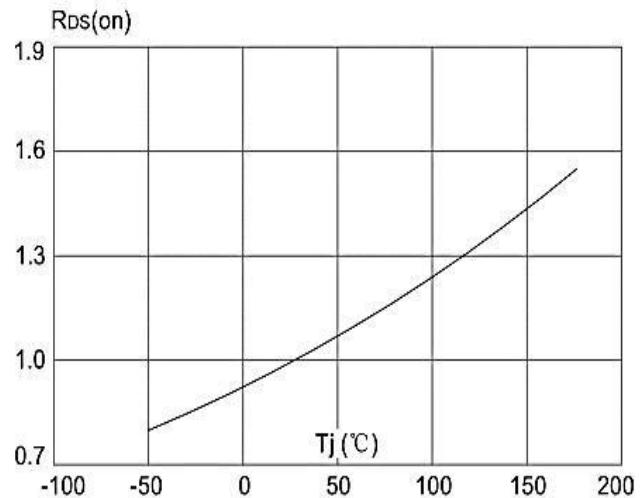


Figure 8: Normalized on Resistance vs. Junction Temperature

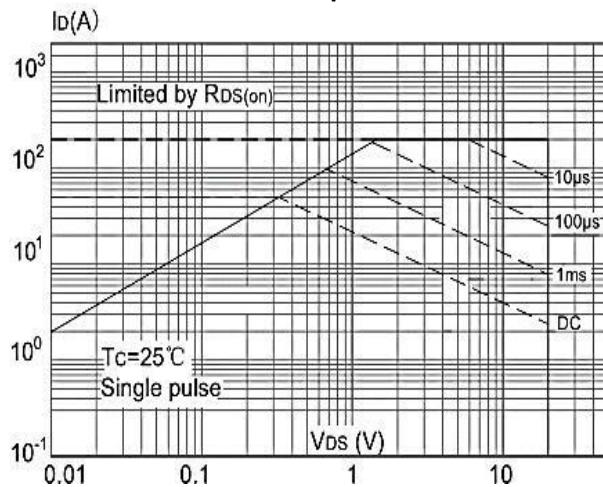


Figure 9: Maximum Safe Operating Area vs. Case Temperature

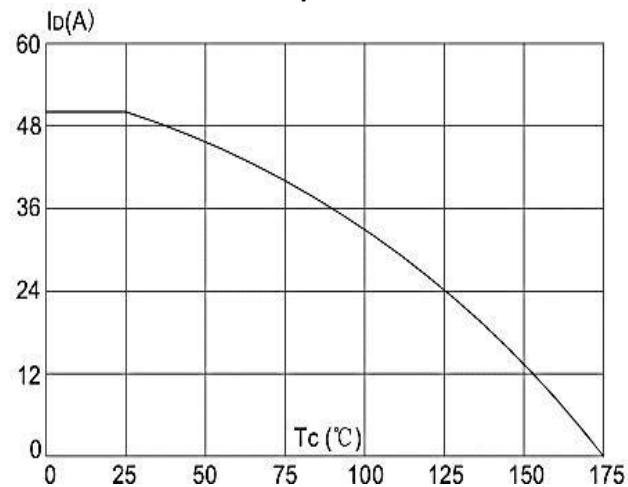


Figure 10: Maximum Continuous Drain Current

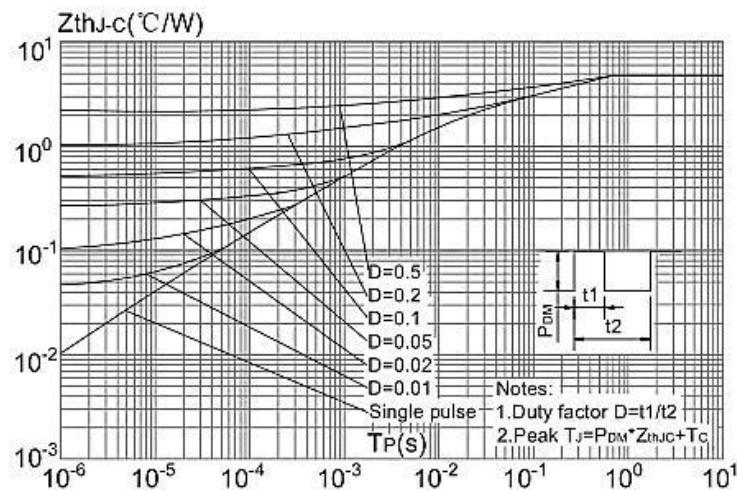
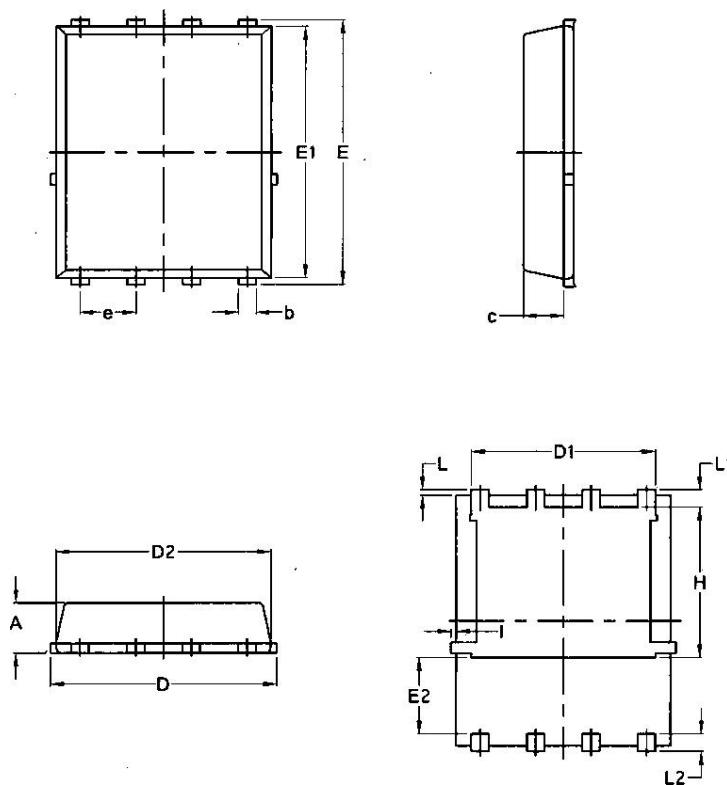


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

Package Mechanical Data-PDFN3*3-8L-JQ Single

COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		